

**Phase leg**  
**Serie & SiC parallel diodes**  
**Super Junction**  
**MOSFET Power Module**

**V<sub>DSS</sub> = 800V**
**R<sub>DSon</sub> = 150mΩ max @ T<sub>j</sub> = 25°C**
**I<sub>D</sub> = 28A @ T<sub>c</sub> = 25°C**
**Application**

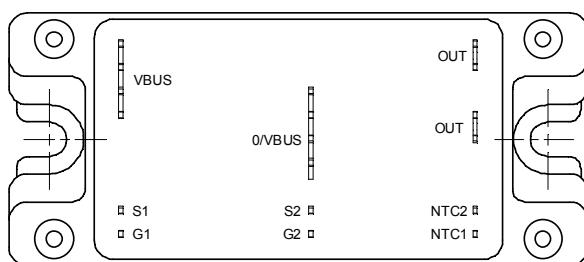
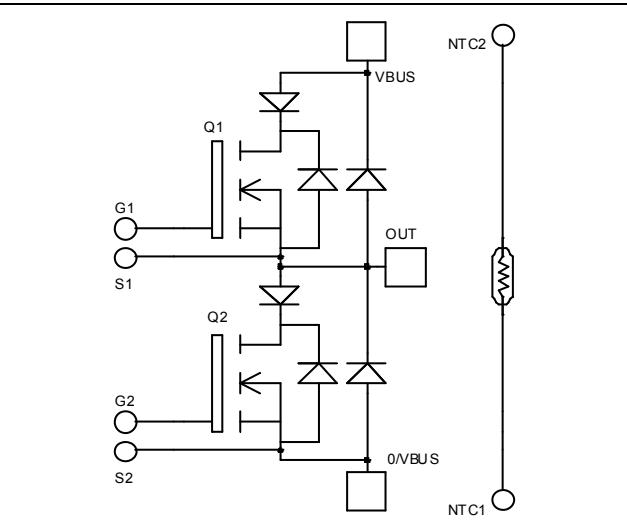
- Motor control
- Switched Mode Power Supplies
- Uninterruptible Power Supplies

**Features**

- **COOLMOS® Power Semiconductors**
  - Ultra low R<sub>DSon</sub>
  - Low Miller capacitance
  - Ultra low gate charge
  - Avalanche energy rated
- **Parallel SiC Schottky Diode**
  - Zero reverse recovery
  - Zero forward recovery
  - Temperature Independent switching behavior
  - Positive temperature coefficient on VF
- Kelvin source for easy drive
- Very low stray inductance
  - Symmetrical design
  - Lead frames for power connections
- Internal thermistor for temperature monitoring
- High level of integration

**Benefits**

- Outstanding performance at high frequency operation
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- Solderable terminals both for power and signal for easy PCB mounting
- Low profile


**Absolute maximum ratings**

Symbol	Parameter	Max ratings	Unit
V <sub>DSS</sub>	Drain - Source Breakdown Voltage	800	V
I <sub>D</sub>	Continuous Drain Current	T <sub>c</sub> = 25°C T <sub>c</sub> = 80°C	28 21
I <sub>DM</sub>	Pulsed Drain current		
V <sub>GS</sub>	Gate - Source Voltage	±30	V
R <sub>DSon</sub>	Drain - Source ON Resistance	150	mΩ
P <sub>D</sub>	Maximum Power Dissipation	T <sub>c</sub> = 25°C	277
I <sub>AR</sub>	Avalanche current (repetitive and non repetitive)		A
E <sub>AR</sub>	Repetitive Avalanche Energy	0.5	mJ
E <sub>AS</sub>	Single Pulse Avalanche Energy	670	

 **CAUTION:** These Devices are sensitive to Electrostatic Discharge. Proper Handing Procedures Should Be Followed.

All ratings @  $T_j = 25^\circ\text{C}$  unless otherwise specified

### Electrical Characteristics

Symbol	Characteristic	Test Conditions		Min	Typ	Max	Unit
$\text{BV}_{\text{DSS}}$	Drain - Source Breakdown Voltage	$V_{\text{GS}} = 0\text{V}, I_D = 500\mu\text{A}$		800			V
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 800\text{V}$	$T_j = 25^\circ\text{C}$			50	$\mu\text{A}$
		$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 800\text{V}$	$T_j = 125^\circ\text{C}$			500	
$R_{\text{DS(on)}}$	Drain – Source on Resistance	$V_{\text{GS}} = 10\text{V}, I_D = 14\text{A}$				150	$\text{m}\Omega$
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}} = V_{\text{DS}}, I_D = 2\text{mA}$		2.1	3	3.9	V
$I_{\text{GSS}}$	Gate – Source Leakage Current	$V_{\text{GS}} = \pm 20\text{ V}, V_{\text{DS}} = 0\text{V}$				$\pm 150$	nA

### Dynamic Characteristics

Symbol	Characteristic	Test Conditions		Min	Typ	Max	Unit
$C_{\text{iss}}$	Input Capacitance	$V_{\text{GS}} = 0\text{V}$ $V_{\text{DS}} = 25\text{V}$ $f = 1\text{MHz}$			4507		pF
$C_{\text{oss}}$	Output Capacitance				2092		
$C_{\text{rss}}$	Reverse Transfer Capacitance				108		
$Q_g$	Total gate Charge	$V_{\text{GS}} = 10\text{V}$ $V_{\text{Bus}} = 400\text{V}$ $I_D = 28\text{A}$			182		nC
$Q_{\text{gs}}$	Gate – Source Charge				24		
$Q_{\text{gd}}$	Gate – Drain Charge				92		
$T_{\text{d(on)}}$	Turn-on Delay Time	<b>Inductive switching @ 125°C</b> $V_{\text{GS}} = 15\text{V}$ $V_{\text{Bus}} = 533\text{V}$ $I_D = 28\text{A}$			10		ns
$T_r$	Rise Time				13		
$T_{\text{d(off)}}$	Turn-off Delay Time				83		
$T_f$	Fall Time		$R_G = 2.5\Omega$		35		
$E_{\text{on}}$	Turn-on Switching Energy	<b>Inductive switching @ 25°C</b> $V_{\text{GS}} = 15\text{V}, V_{\text{Bus}} = 533\text{V}$ $I_D = 28\text{A}, R_G = 2.5\Omega$			292		$\mu\text{J}$
$E_{\text{off}}$	Turn-off Switching Energy ①				278		
$E_{\text{on}}$	Turn-on Switching Energy		<b>Inductive switching @ 125°C</b> $V_{\text{GS}} = 15\text{V}, V_{\text{Bus}} = 533\text{V}$ $I_D = 28\text{A}, R_G = 2.5\Omega$		510		$\mu\text{J}$
$E_{\text{off}}$	Turn-off Switching Energy ①				342		

① In accordance with JEDEC standard JESD24-1.

### Series diode ratings and characteristics

Symbol	Characteristic	Test Conditions		Min	Typ	Max	Unit
$I_{\text{F(AV)}}$	Maximum Average Forward Current	50% duty cycle	$T_c = 85^\circ\text{C}$		30		A
$V_F$	Diode Forward Voltage	$I_F = 30\text{A}$			1.1	1.15	V
		$I_F = 60\text{A}$			1.4		
		$I_F = 30\text{A}$	$T_j = 125^\circ\text{C}$		0.9		
$t_{\text{rr}}$	Reverse Recovery Time	$I_F = 30\text{A}$	$T_j = 25^\circ\text{C}$		24		ns
		$V_R = 133\text{V}$	$T_j = 125^\circ\text{C}$		48		
$Q_{\text{rr}}$	Reverse Recovery Charge	$I_F = 30\text{A}$	$T_j = 25^\circ\text{C}$		33		nC
		$V_R = 133\text{V}$	$T_j = 125^\circ\text{C}$		150		

### **Parallel diode ratings and characteristics**

Symbol	Characteristic	Test Conditions		Min	Typ	Max	Unit
I <sub>F(AV)</sub>	Maximum Average Forward Current	50% duty cycle	T <sub>c</sub> = 125°C		15		A
V <sub>F</sub>	Diode Forward Voltage	I <sub>F</sub> = 15A	T <sub>j</sub> = 25°C		1.6	1.8	V
			T <sub>j</sub> = 175°C		2.6	3.0	
Q <sub>C</sub>	Total Capacitive Charge	I <sub>F</sub> = 15A, V <sub>R</sub> = 600V di/dt = 1000A/μs			42		nC
Q	Total Capacitance	f = 1MHz, V <sub>R</sub> = 200V			135		pF
		f = 1MHz, V <sub>R</sub> = 400V			99		

## Thermal and package characteristics

Terminal and package characteristics		Symbol	Characteristic	Min	Typ	Max	Unit
$R_{thJC}$	Junction to Case	Transistor			0.45	°C/W	
		Series diode			1.2		
		Parallel diode			1.0		
$V_{ISOL}$	RMS Isolation Voltage, any terminal to case t =1 min, $I_{isol} < 1\text{mA}$ , 50/60Hz		2500			V	
$T_J$	Operating junction temperature range		-40		150	°C	
$T_{STG}$	Storage Temperature Range		-40		125		
$T_C$	Operating Case Temperature		-40		100		
Torque	Mounting torque	To Heatsink	M5			4.7	N.m
Wt	Package Weight					160	g

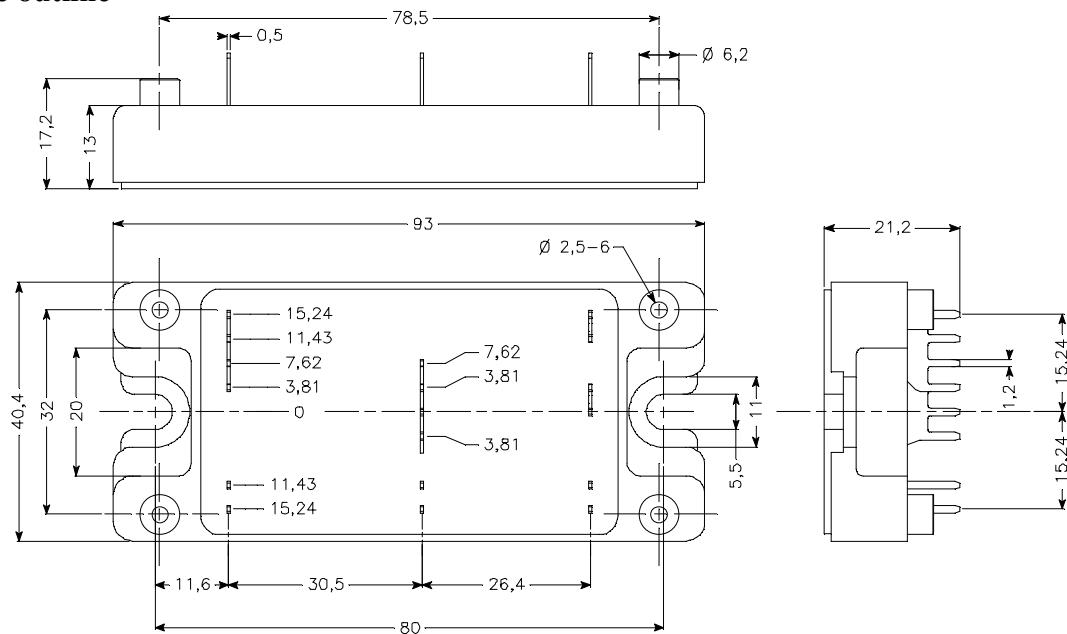
## Temperature sensor NTC

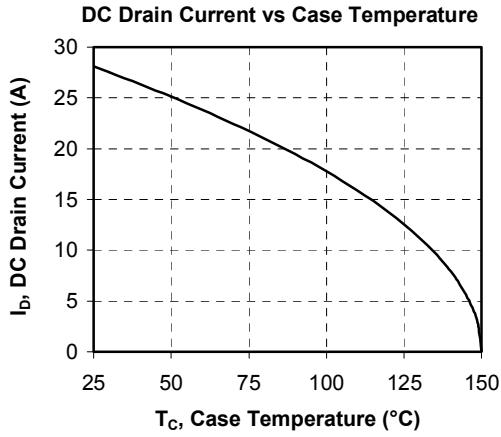
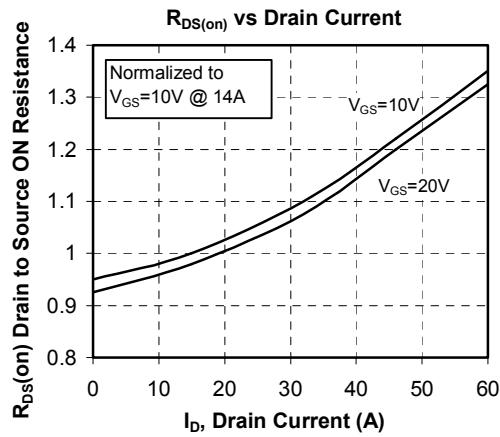
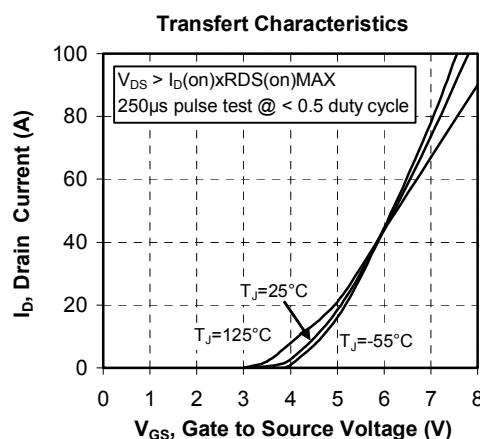
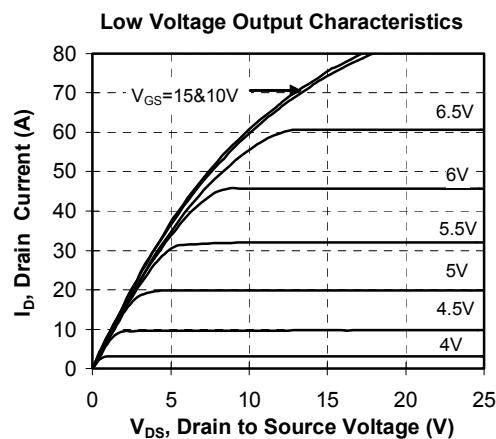
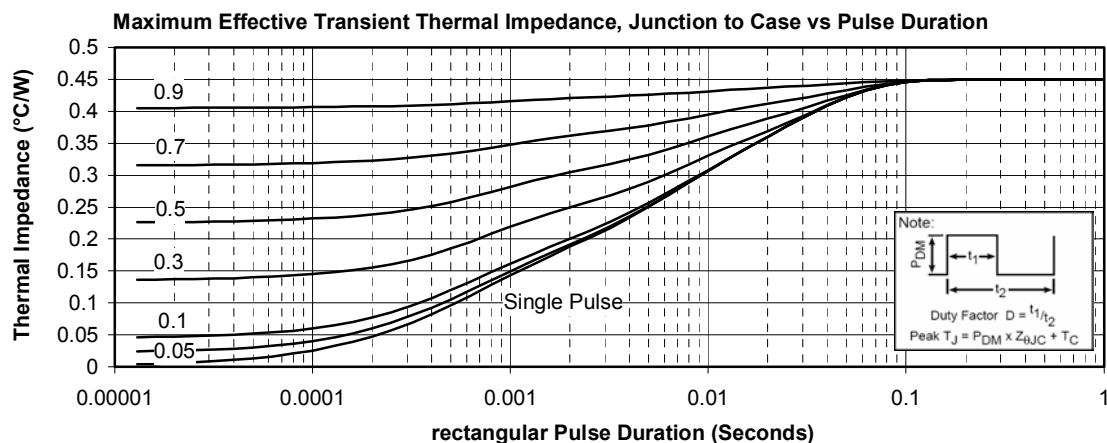
<b>Symbol</b>	<b>Characteristic</b>	<b>Min</b>	<b>Typ</b>	<b>Max</b>	<b>Unit</b>
R <sub>25</sub>	Resistance @ 25°C		68		kΩ
B <sub>25/85</sub>	T <sub>25</sub> = 298.16 K		4080		K

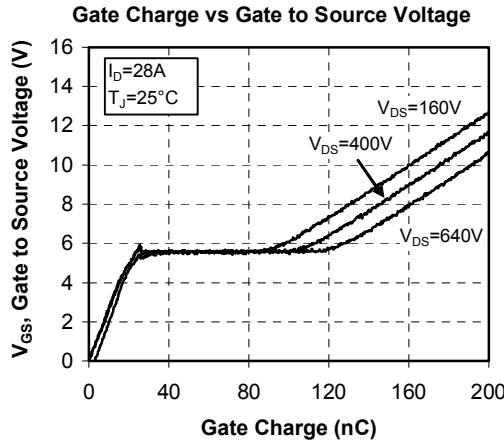
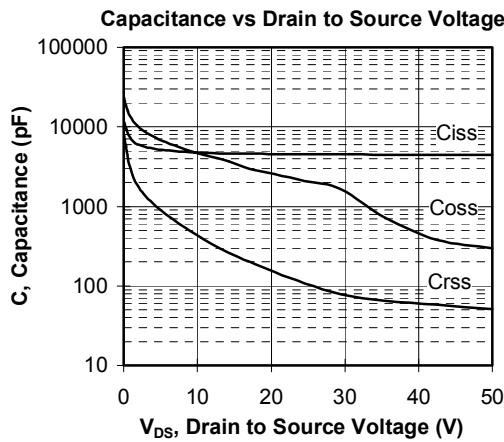
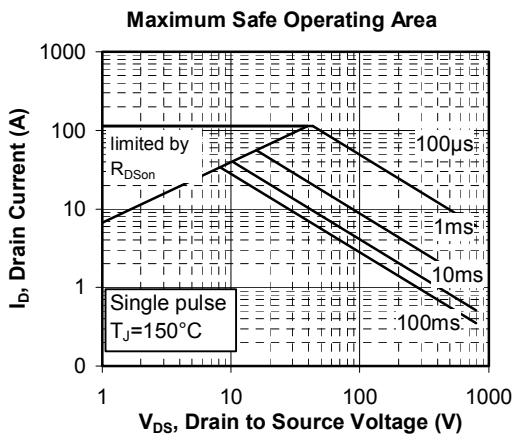
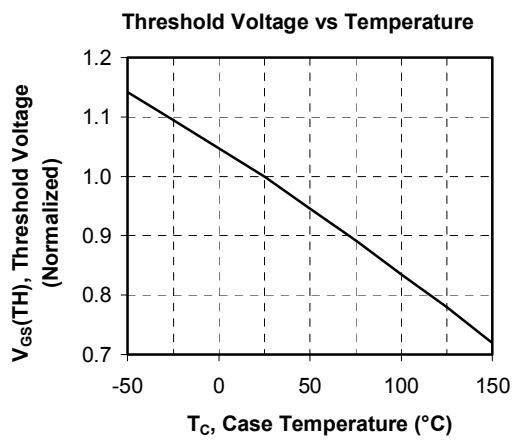
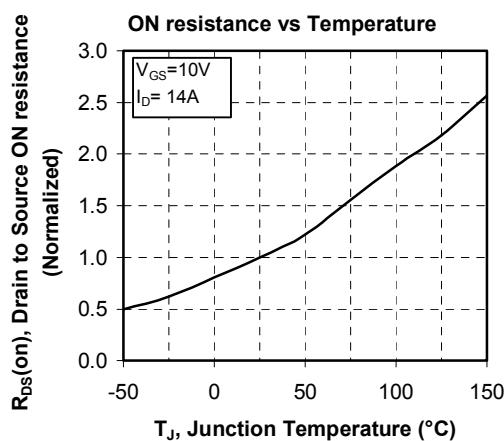
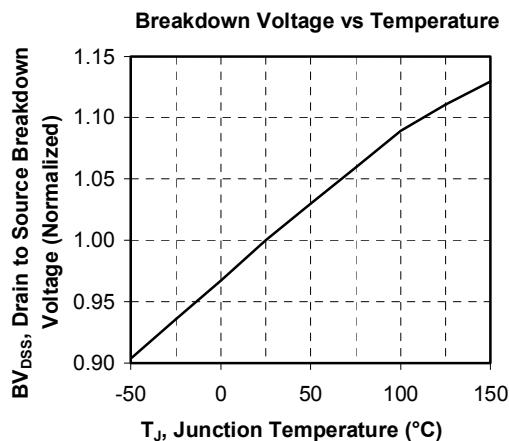
$$R_T = \frac{R_{25}}{\exp\left[B_{25/85}\left(\frac{1}{T_{25}} - \frac{1}{T}\right)\right]}$$

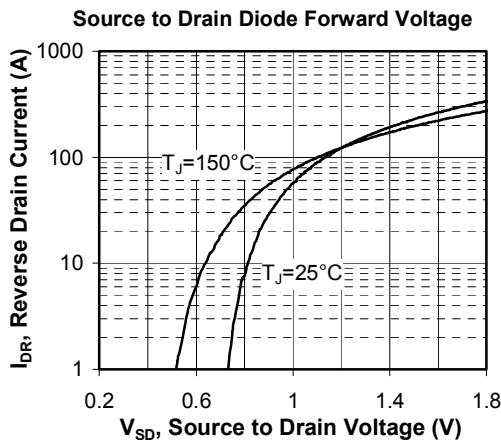
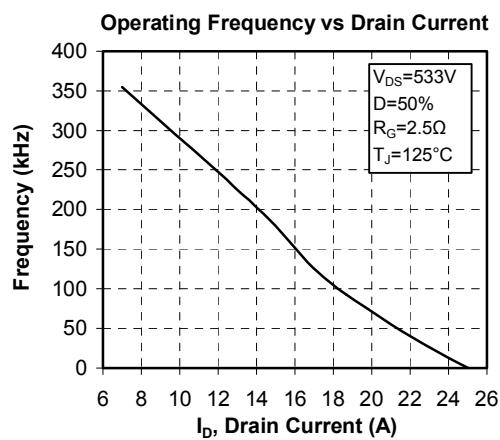
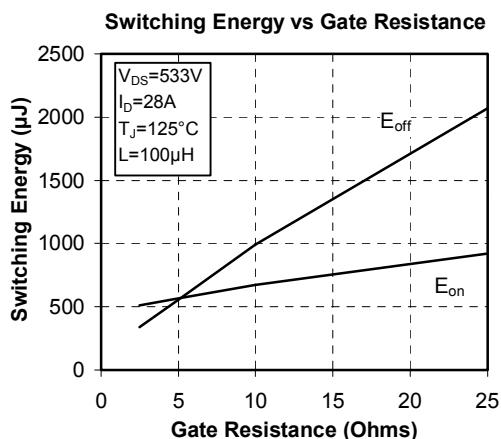
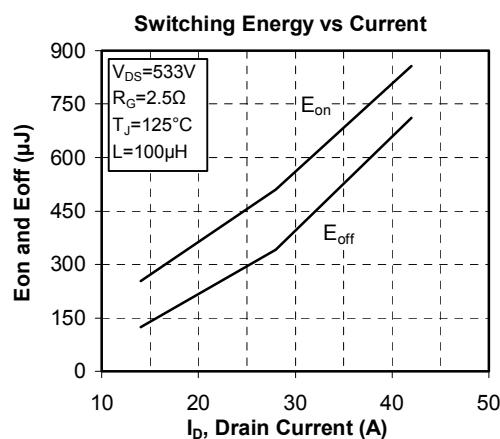
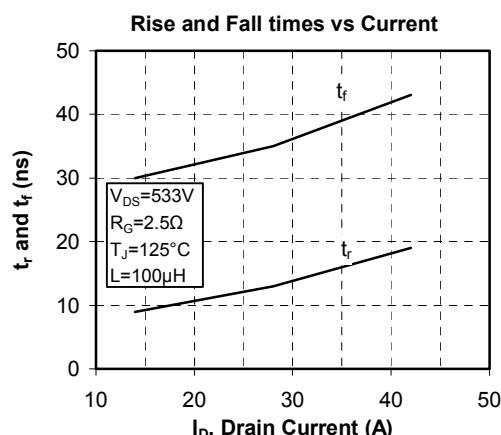
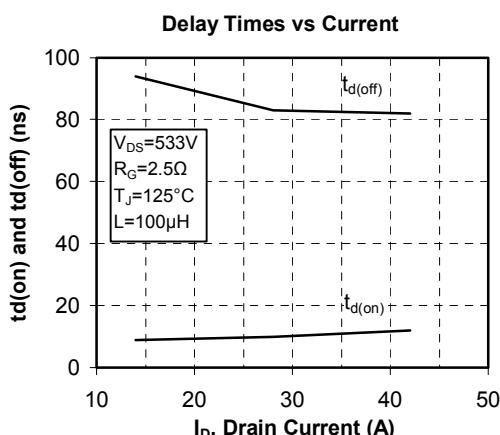
T: Thermistor temperature  
R<sub>T</sub>: Thermistor value at T

## Package outline



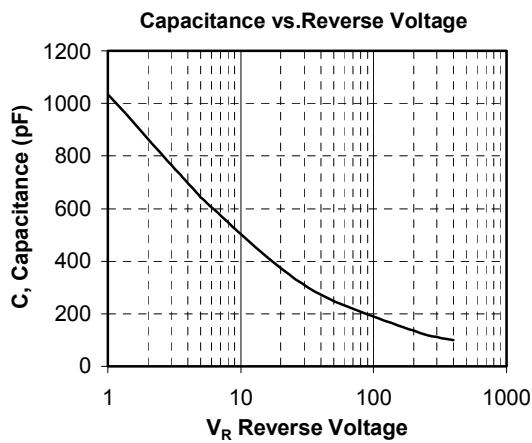
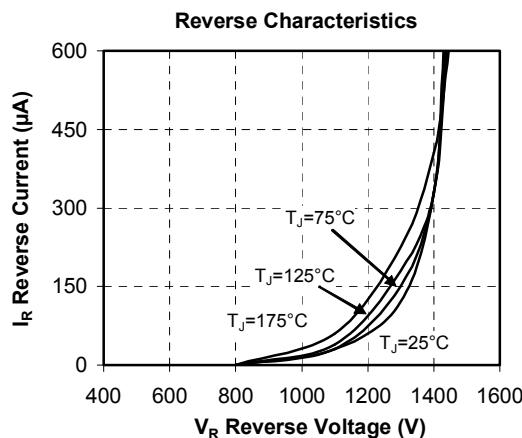
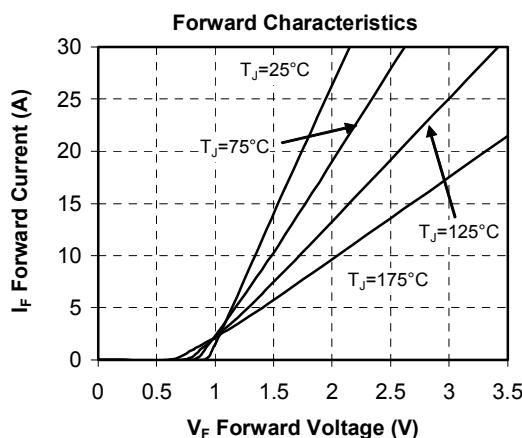
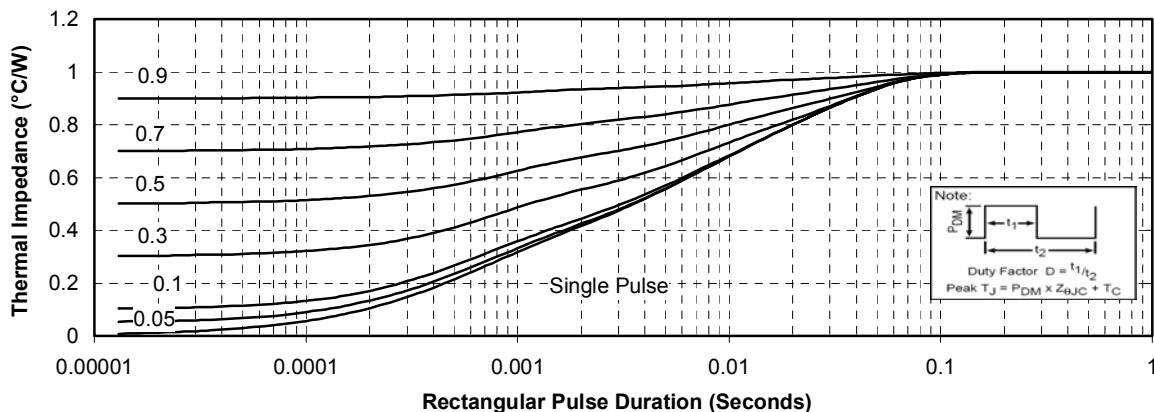
**Typical CoolMOS Performance Curve**






### Typical SiC Diode Performance Curve

Maximum Effective Transient Thermal Impedance, Junction to Case vs Pulse Duration



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APT's products are covered by one or more of U.S patents 4,895,810 5,045,903 5,089,434 5,182,234 5,019,522 5,262,336 6,503,786 5,256,583 4,748,103 5,283,202 5,231,474 5,434,095 5,528,058 and foreign patents. U.S and Foreign patents pending. All Rights Reserved.